

Document Title

512Kx8 Bit High Speed Static RAM(5V Operating), Revolutionary Pin out.
Operated at Commercial Temperature Range.

Revision History

<u>RevNo.</u>	<u>History</u>	<u>Draft Data</u>	<u>Remark</u>																					
Rev. 0.0	Initial release with Design Target.	Jun. 14th, 1996	Design Target																					
Rev. 0.5	Release to Preliminary Data Sheet. 0.1. Replace Design Target to Preliminary. 0.2. Delete 12ns part but add 17ns part. 0.3. Relax D.C and A.C parameters and insert new parameter(Icc1) with the test condition. 0.3.1. Insert Icc1 parameter with the test condition as address is increased with binary count. 0.3.2. Relax D.C and A.C parameters.	Sep. 16th, 1996	Preliminary																					
	<table><tr><td>Items</td><td>Previous spec. (15/ - /20ns part)</td><td>Relaxed spec. (15/17/20ns part)</td></tr><tr><td>Icc</td><td>190/ - /180mA</td><td>220/215/210mA</td></tr><tr><td>tcw</td><td>10/ - /12ns</td><td>12/13/14ns</td></tr><tr><td>tAW</td><td>10/ - /12ns</td><td>12/13/14ns</td></tr><tr><td>tWP($\overline{OE}=H$)</td><td>10/ - /12ns</td><td>12/13/14ns</td></tr><tr><td>tWP1($\overline{OE}=L$)</td><td>12/ - /14ns</td><td>15/17/20ns</td></tr><tr><td>tdw</td><td>7/ - /9ns</td><td>8/9/10ns</td></tr></table>	Items	Previous spec. (15/ - /20ns part)	Relaxed spec. (15/17/20ns part)	Icc	190/ - /180mA	220/215/210mA	tcw	10/ - /12ns	12/13/14ns	tAW	10/ - /12ns	12/13/14ns	tWP($\overline{OE}=H$)	10/ - /12ns	12/13/14ns	tWP1($\overline{OE}=L$)	12/ - /14ns	15/17/20ns	tdw	7/ - /9ns	8/9/10ns		
Items	Previous spec. (15/ - /20ns part)	Relaxed spec. (15/17/20ns part)																						
Icc	190/ - /180mA	220/215/210mA																						
tcw	10/ - /12ns	12/13/14ns																						
tAW	10/ - /12ns	12/13/14ns																						
tWP($\overline{OE}=H$)	10/ - /12ns	12/13/14ns																						
tWP1($\overline{OE}=L$)	12/ - /14ns	15/17/20ns																						
tdw	7/ - /9ns	8/9/10ns																						
Rev. 1.0	Release to Final Data Sheet. 1.1. Delete Preliminary. 1.2. Delete Icc1 parameter with the test condition. 1.3. Update D.C parameters.	Jun. 5th, 1997	Final																					
	<table><tr><td>Items</td><td>Previous spec. (15/17/20ns part)</td><td>Updated spec. (15/17/20ns part)</td></tr><tr><td>Icc</td><td>220/215/210mA</td><td>170/165/160mA</td></tr></table> 1.4. Add the test condition for VOH1 with Vcc=5V±5% at 25°C 1.5. Add timing <u>diagram</u> to define tWP as "(Timing Wave Form of Write Cycle(CS=Low fixed))"	Items	Previous spec. (15/17/20ns part)	Updated spec. (15/17/20ns part)	Icc	220/215/210mA	170/165/160mA																	
Items	Previous spec. (15/17/20ns part)	Updated spec. (15/17/20ns part)																						
Icc	220/215/210mA	170/165/160mA																						
Rev. 2.0	2.1 Add extended and industrial temperature range parts.	Jun. 5th, 1997	Final																					

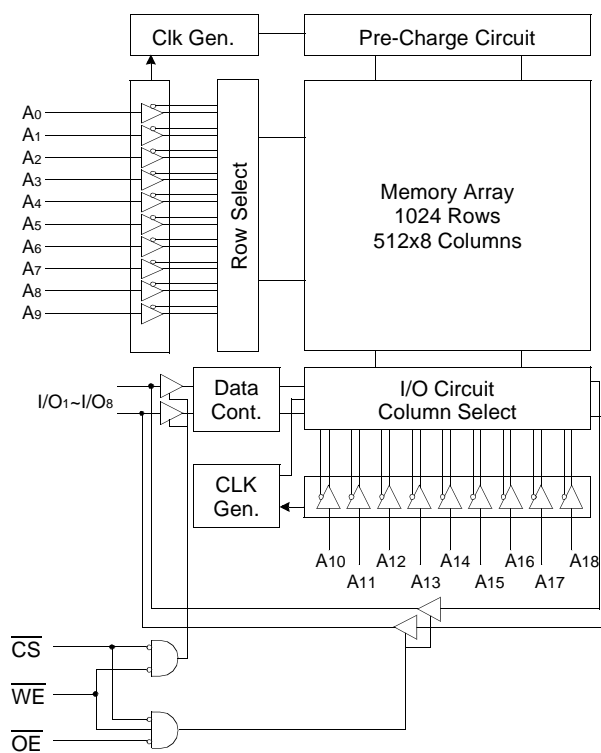
The attached data sheets are prepared and approved by SAMSUNG Electronics. SAMSUNG Electronics CO., LTD. reserve the right to change the specifications. SAMSUNG Electronics will evaluate and reply to your requests and questions on the parameters of this device. If you have any questions, please contact the SAMSUNG branch office near your office, call or contact Headquarters.

512K x 8 Bit High-Speed CMOS Static RAM
FEATURES

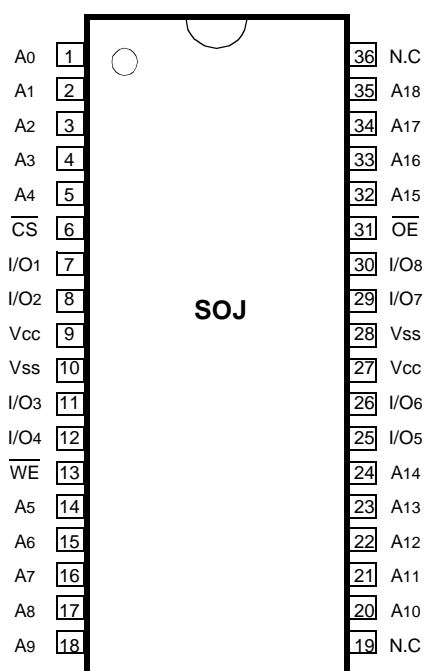
- Fast Access Time 15,17,20ns(Max.)
- Low Power Dissipation
 - Standby (TTL) : 50mA(Max.)
 - (CMOS) : 10mA(Max.)
 - Operating KM684002A - 15 : 170mA(Max.)
 - KM684002A - 17 : 165mA(Max.)
 - KM684002A - 20 : 160mA(Max.)
- Single 5.0V±10% Power Supply
- TTL Compatible Inputs and Outputs
- I/O Compatible with 3.3V Device
- Fully Static Operation
 - No Clock or Refresh required
- Three State Outputs
- Center Power/Ground Pin Configuration
- Standard Pin Configuration
 - KM684002AJ : 36-SOJ-400

ORDERING INFORMATION

KM684002A-15/17/20	Commercial Temp.
KM684002AE-15/17/20	Extended Temp.
KM684002AI-15/17/20	Industrial Temp.

FUNCTIONAL BLOCK DIAGRAM

GENERAL DESCRIPTION

The KM684002A is a 4,194,304-bit high-speed Static Random Access Memory organized as 524,288 words by 8 bits. The KM684002A uses 8 common input and output lines and has an output enable pin which operates faster than address access time at read cycle. The device is fabricated using SAMSUNG's advanced CMOS process and designed for high-speed circuit technology. It is particularly well suited for use in high-density high-speed system applications. The KM684002A is packaged in a 400mil 36-pin plastic SOJ.

PIN CONFIGURATION (Top View)

PIN FUNCTION

Pin Name	Pin Function
A0 - A18	Address Inputs
\overline{WE}	Write Enable
\overline{CS}	Chip Select
\overline{OE}	Output Enable
I/O1 ~ I/O8	Data Inputs/Outputs
Vcc	Power(+5.0V)
Vss	Ground
N.C	No Connection

ABSOLUTE MAXIMUM RATINGS*

Parameter		Symbol	Rating	Unit
Voltage on Any Pin Relative to V _{SS}		V _{IN} , V _{OUT}	-0.5 to 7.0	V
Voltage on V _{CC} Supply Relative to V _{SS}		V _{CC}	-0.5 to 7.0	V
Power Dissipation		P _D	1.0	W
Storage Temperature		T _{STG}	-65 to 150	°C
Operating Temperature	Commercial	T _A	0 to 70	°C
	Extended	T _A	-25 to 85	°C
	Industrial	T _A	-40 to 85	°C

* Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

RECOMMENDED DC OPERATING CONDITIONS(T_A=0 to 70°C)

Parameter	Symbol	Min	Typ	Max	Unit
Supply Voltage	V _{CC}	4.5	5.0	5.5	V
Ground	V _{SS}	0	0	0	V
Input High Voltage	V _{IH}	2.2	-	V _{CC} +0.5**	V
Input Low Voltage	V _{IL}	-0.5*	-	0.8	V

NOTE: The above parameters are also guaranteed at extended and industrial temperature ranges.

* V_{IL}(Min) = -2.0V a.c(Pulse Width ≤ 10ns) for I ≤ 20mA

** V_{IH}(Max) = V_{CC} + 2.0V a.c (Pulse Width ≤ 10ns) for I ≤ 20mA

DC AND OPERATING CHARACTERISTICS(T_A=0 to 70°C, V_{CC}=5.0V±10%, unless otherwise specified)

Parameter	Symbol	Test Conditions		Min	Max	Unit
Input Leakage Current	I _{LI}	V _{IN} =V _{SS} to V _{CC}		-2	2	μA
Output Leakage Current	I _{LO}	CS=V _{IH} or OE=V _{IH} or WE=V _{IL} V _{OUT} =V _{SS} to V _{CC}		-2	2	μA
Operating Current	I _{CC}	Min. Cycle, 100% Duty CS=V _{IL} , V _{IN} =V _{IH} or V _{IL} , I _{OUT} =0mA	15ns	-	170	mA
			17ns	-	165	
			20ns	-	160	
Standby Current	I _{SB}	Min. Cycle, CS=V _{IH}		-	50	mA
	I _{SB1}	f=0MHz, CS≥V _{CC} -0.2V, V _{IN} ≥V _{CC} -0.2V or V _{IN} ≤0.2V		-	10	
Output Low Voltage Level	V _{OL}	I _{OL} =8mA		-	0.4	V
Output High Voltage Level	V _{OH}	I _{OH} =-4mA		2.4	-	V
	V _{OH1} *	I _{OH1} =-100μA		-	3.95	

NOTE: The above parameters are also guaranteed at extended and industrial temperature ranges.

* V_{CC}=5.0V, Temp.=25°C

CAPACITANCE*(T_A=25°C, f=1.0MHz)

Item	Symbol	Test Conditions	MIN	Max	Unit
Input/Output Capacitance	C _{I/O}	V _{I/O} =0V	-	8	pF
Input Capacitance	C _{IN}	V _{IN} =0V	-	7	pF

* NOTE : Capacitance is sampled and not 100% tested.

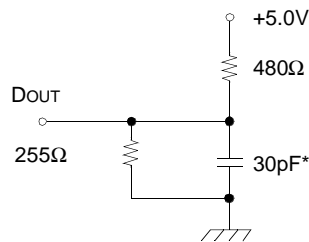
AC CHARACTERISTICS (TA=0 to 70°C, VCC=5.0V±10%, unless otherwise noted.)

TEST CONDITIONS

Parameter	Value
Input Pulse Levels	0V to 3V
Input Rise and Fall Times	3ns
Input and Output timing Reference Levels	1.5V
Output Loads	See below

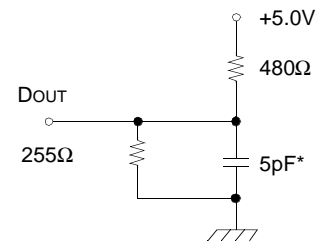
NOTE: The above parameters are also guaranteed at extended and industrial temperature ranges.

Output Loads(A)



Output Loads(B)

for tHZ, tLZ, tWHZ, tOW, tOLZ & tOHZ



* Including Scope and Jig Capacitance

READ CYCLE

Parameter	Symbol	KM684002A-15		KM684002A-17		KM684002A-20		Unit
		Min	Max	Min	Max	Min	Max	
Read Cycle Time	tRC	15	-	17	-	20	-	ns
Address Access Time	tAA	-	15	-	17	-	20	ns
Chip Select to Output	tCO	-	15	-	17	-	20	ns
Output Enable to Valid Output	tOE	-	7	-	8	-	9	ns
Chip Enable to Low-Z Output	tLZ	3	-	3	-	3	-	ns
Output Enable to Low-Z Output	tOLZ	0	-	0	-	0	-	ns
Chip Disable to High-Z Output	tHZ	0	7	0	8	0	9	ns
Output Disable to High-Z Output	tOHZ	0	7	0	8	0	9	ns
Output Hold from Address Change	tOH	3	-	3	-	3	-	ns
Chip Selection to Power Up Time	tPU	0	-	0	-	0	-	ns
Chip Selection to Power Down Time	tPD	-	15	-	17	-	20	ns

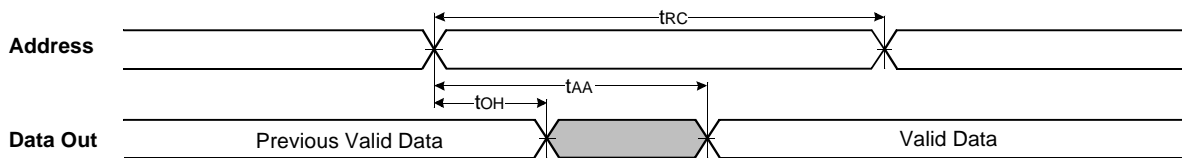
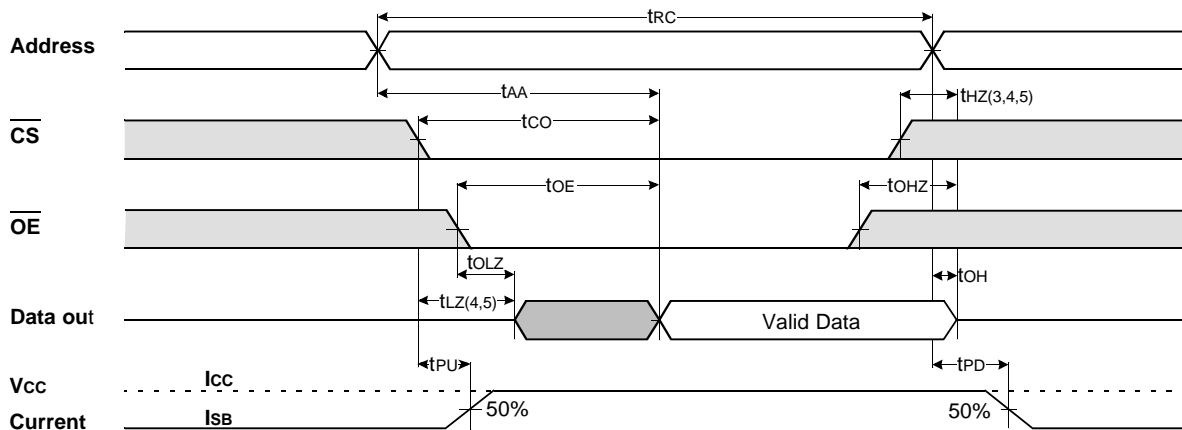
NOTE: The above parameters are also guaranteed at extended and industrial temperature ranges.

WRITE CYCLE

Parameter	Symbol	KM684002A-15		KM684002A-17		KM684002A-20		Unit
		Min	Max	Min	Max	Min	Max	
Write Cycle Time	t _{WC}	15	-	17	-	20	-	ns
Chip Select to End of Write	t _{CW}	12	-	13	-	14	-	ns
Address Set-up Time	t _{AS}	0	-	0	-	0	-	ns
Address Valid to End of Write	t _{AW}	12	-	13	-	14	-	ns
Write Pulse Width($\overline{\text{OE}}$ High)	t _{WP}	12	-	13	-	14	-	ns
Write Pulse Width($\overline{\text{OE}}$ Low)	t _{WP1}	15	-	17	-	20	-	ns
Write Recovery Time	t _{WR}	0	-	0	-	0	-	ns
Write to Output High-Z	t _{WHZ}	0	7	0	8	0	9	ns
Data to Write Time Overlap	t _{DW}	8	-	9	-	10	-	ns
Data Hold from Write Time	t _{DH}	0	-	0	-	0	-	ns
End Write to Output Low-Z	t _{OW}	3	-	3	-	3	-	ns

NOTE: The above parameters are also guaranteed at extended and industrial temperature ranges.

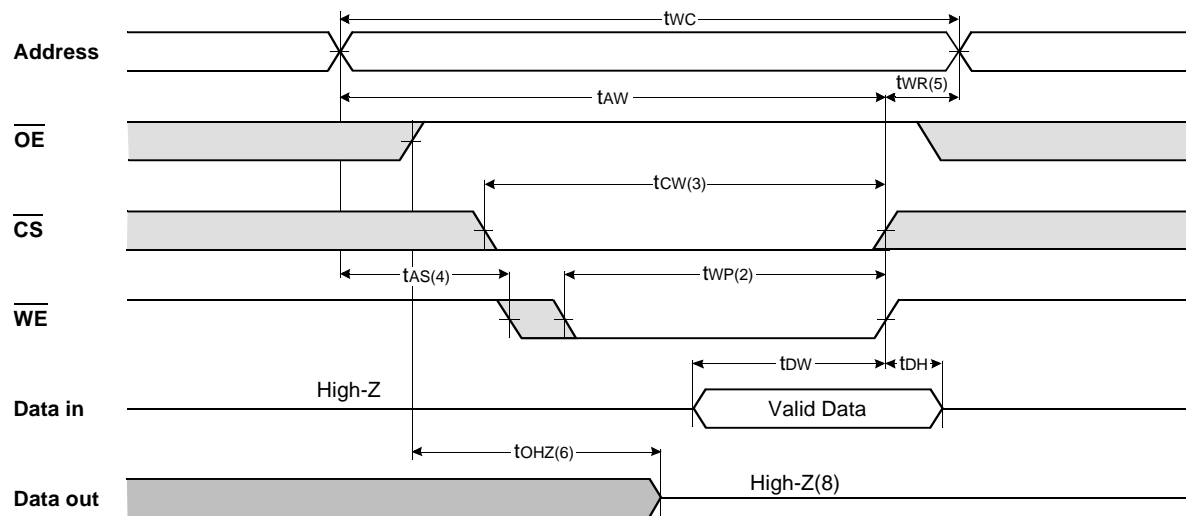
TIMMING DIAGRAMS

TIMING WAVEFORM OF READ CYCLE(1) (Address Controlled, $\overline{\text{CS}}=\overline{\text{OE}}=V_{\text{IL}}$, $\overline{\text{WE}}=V_{\text{IH}}$)TIMING WAVEFORM OF READ CYCLE(2) ($\overline{\text{WE}}=V_{\text{IH}}$)

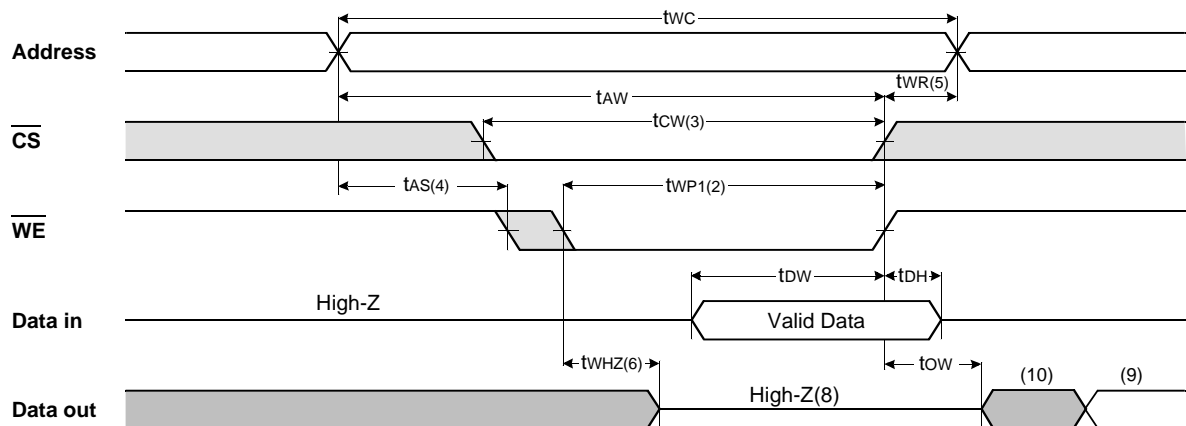
NOTES(READ CYCLE)

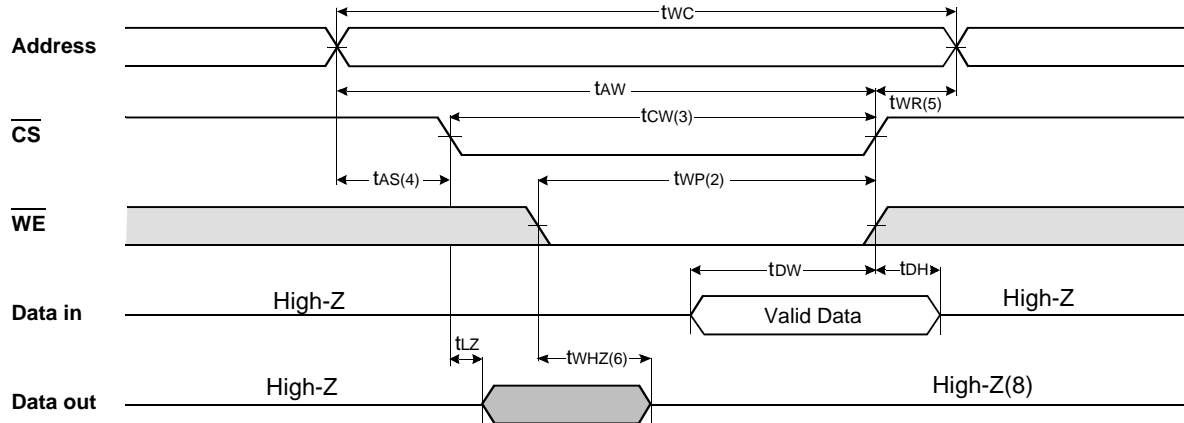
1. \overline{WE} is high for read cycle.
2. All read cycle timing is referenced from the last valid address to the first transition address.
3. t_{HZ} and t_{OHZ} are defined as the time at which the outputs achieve the open circuit condition and are not referenced to V_{OH} or V_{OL} levels.
4. At any given temperature and voltage condition, $t_{HZ}(\text{Max.})$ is less than $t_{LZ}(\text{Min.})$ both for a given device and from device to device.
5. Transition is measured $\pm 200\text{mV}$ from steady state voltage with Load(B). This parameter is sampled and not 100% tested.
6. Device is continuously selected with $\overline{CS}=V_{IL}$.
7. Address valid prior to coincident with \overline{CS} transition low.
8. For common I/O applications, minimization or elimination of bus contention conditions is necessary during read and write cycle.

TIMING WAVEFORM OF WRITE CYCLE(1) ($\overline{OE} = \text{Clock}$)



TIMING WAVEFORM OF WRITE CYCLE(2) ($\overline{OE} = \text{Low Fixed}$)



TIMING WAVEFORM OF WRITE CYCLE(3) ($\overline{\text{CS}}$ = Controlled)

NOTES(WRITE CYCLE)

1. All write cycle timing is referenced from the last valid address to the first transition address.
2. A write occurs during the overlap of a low $\overline{\text{CS}}$ and $\overline{\text{WE}}$. A write begins at the latest transition $\overline{\text{CS}}$ going low and $\overline{\text{WE}}$ going low ; A write ends at the earliest transition $\overline{\text{CS}}$ going high or $\overline{\text{WE}}$ going high. t_{WP} is measured from the beginning of write to the end of write.
3. t_{CW} is measured from the later of $\overline{\text{CS}}$ going low to end of write.
4. t_{AS} is measured from the address valid to the beginning of write.
5. t_{WR} is measured from the end of write to the address change. t_{WR} applied in case a write ends as $\overline{\text{CS}}$ or $\overline{\text{WE}}$ going high.
6. If $\overline{\text{OE}}$, $\overline{\text{CS}}$ and $\overline{\text{WE}}$ are in the Read Mode during this period, the I/O pins are in the output low-Z state. Inputs of opposite phase of the output must not be applied because bus contention can occur.
7. For common I/O applications, minimization or elimination of bus contention conditions is necessary during read and write cycle.
8. If $\overline{\text{CS}}$ goes low simultaneously with $\overline{\text{WE}}$ going or after $\overline{\text{WE}}$ going low, the outputs remain high impedance state.
9. Dout is the read data of the new address.
10. When $\overline{\text{CS}}$ is low : I/O pins are in the output state. The input signals in the opposite phase leading to the output should not be applied.

FUNCTIONAL DESCRIPTION

$\overline{\text{CS}}$	$\overline{\text{WE}}$	$\overline{\text{OE}}$	Mode	I/O Pin	Supply Current
H	X	X*	Not Select	High-Z	I_{SB} , I_{SB1}
L	H	H	Output Disable	High-Z	I_{CC}
L	H	L	Read	DOUT	I_{CC}
L	L	X	Write	DIN	I_{CC}

* NOTE : X means Don't Care.

PACKAGE DIMENSIONS

36-SOJ-400

Units: millimeters/Inches

